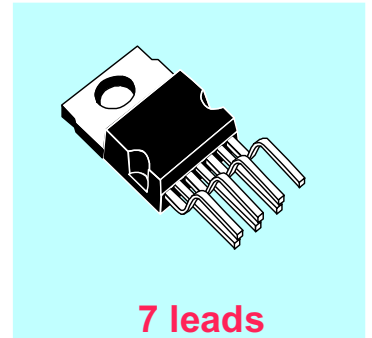
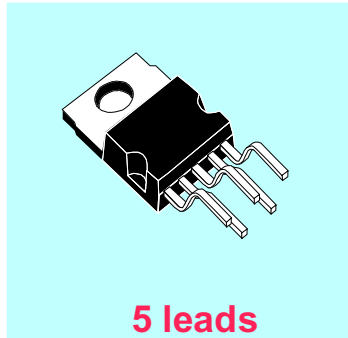
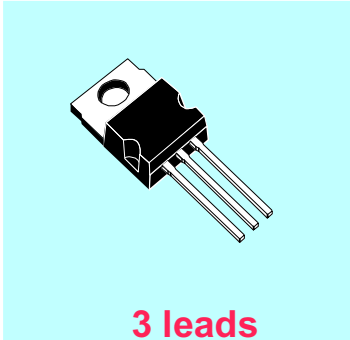


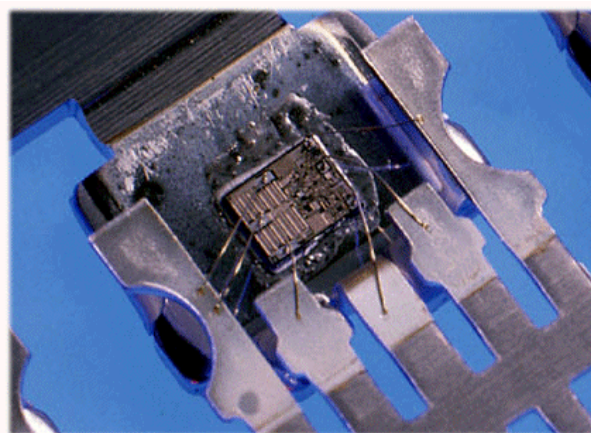
TO-220, PENTAWATT, HEPTAWATT 3,5,7 leads



PACKAGE MATERIAL LIST

item #	material	thickness	thermal conductivity
leadframe	copper	0.5 mm	3.9 W/cm°C
slug	high thermal conductivity Cu	1.27 mm	3.9 W/cm°C
die attach	sof solder (tin lead)	15-50 µm	0.2 W/cm°C
molding compound	epoxy resin	3 mm	0.0063W/cm°C

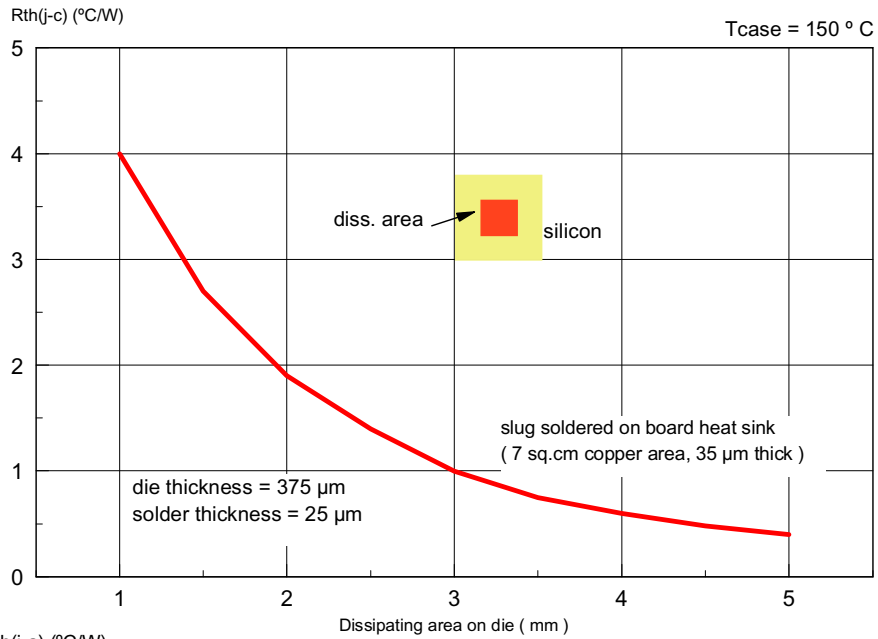
Typical assembly configuration before molding :



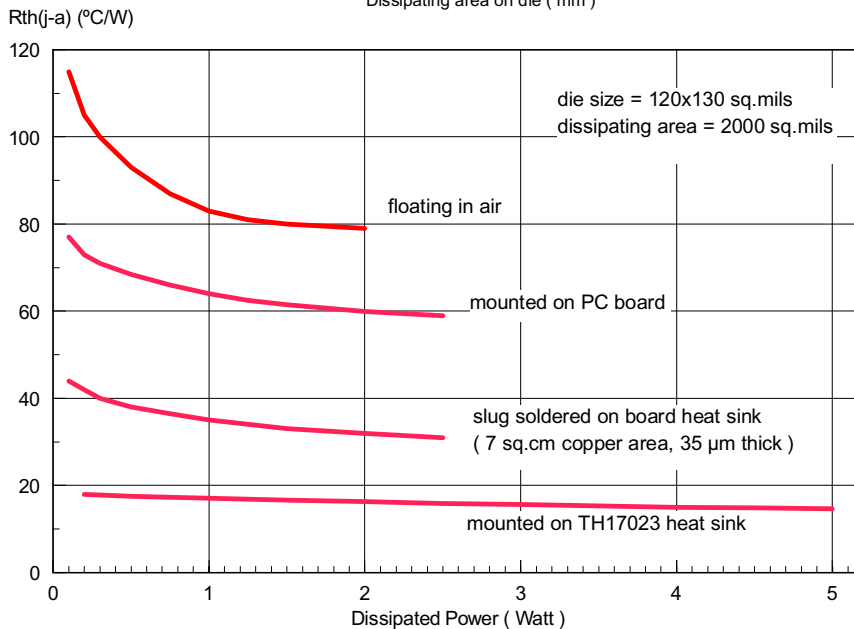
Charts enclosed :

- 1)** $R_{th(j-c)}$ vs. die size and dissipating area
- 2)** $R_{th(j-a)}$ vs on board heat sink area
- 3)** $Z_{th(j-a)}$ vs time width and die size

1)



2)



3)

